Wafer configuration	
1) Substrate	Silicon
2) Diameter	200 +/- 0.2 mm
3) Thickness	0.725 +/- 0.02 mm
4) Orientation	Notch
5) Notch dimensions	Depth 1+0/+0.25mm
	Angle: 90 +1/+5 deg.
Outer dimensions	
(Main system)	W 2000 x D 3490 x H 2450 (mm)
(Power supply)	W 1000 x D 600 x H 1775 (mm)
Maintenance dimensions	
(Main system)	W 3600 x D 4290 x H 2850 (mm)
(Power supply)	W 1000 x D 1600 x H 2175 (mm)
Weight	
(Main system)	6200 (kg)
(Power supply)	650 (kg)
(Operation panel)	60 (kg)

Configuration	qty present	comments
1) Load/Unload port	1x	
2) Wafer station	1x	
3) Wafer transfer robot	3x	Robot D, Robot R, L
4) Polisher unit	2x	Normal head
1) Head	2x	
2) Dresser	2x	Ring type
3) Turn Table	2x	
5) Buffing Table	2x	
6) 1st stage cleaner unit (Both side clean)	2x	Pencil present, sponge head missing
7) 2nd stage cleaner unit (Both side clean)	2x	Roll/Roll
8) Rotary transporter	1x	
9) Filter unit	3x	
10) Power Supply Control Box	1x	
11) Turnover (Both side T/O)	2x	

Power Supply	
1. Circuit Breaker	Independently installed on each module
2. Back up power supply	CPU backup using UPS
3. Main controller	
1) Hardware	VME bus, Board computer
	Main CPU : 68 series 32 bits
2) O/S software	OS-9/C language description
	Separate structure on each Module
3) I/O connections with Module	Serial communication

4. Operation controller

	Touch panel display
1) Method	
2) Location	Front

5. Option
1) MPM

General Configuration

Item	Standard Spec	Remarks
1. Main frame	2 base frame for Polish and Clean unit	
2) Material	Frame : Stainless steel Base/panel : Steel painted Duct/cleaner casting Drain pan : PVC : PVC	
3) Paint	White, Blue and Gray	
4) Panel removal	Latch type + Bolts	
5) Doors	Removable hinged type	

2. Airflow design (Transfer/Cleaner unit)

1) Air circulation	Filtering fan unit (ULPA filter 0.1μm equipped)
2) Local ventilation	All clean units, Cleaner Filter unit installed roof of
3) Clean air inlet	System

3. Airflow design (Polisher unit)

1). Local Ventilation	Around Turn table
2). Clean air unit	Air from transfer/clean unit

4. Piping

1) Material	D.I.Water : PFA (Nippon Pillar super fitting) Slurry : PFA and PTFE (Nippon Pillar super fitting) Drain : PVC

Utility Connections

1. Power supply	AC208V 3 phase 50 / 60 Hz	
	Rated capacity	45KVA
	Full load amperes	80A
	MCB size	125AT
2. D.I. water	Max Flow rate	40 L/min
	Normal Flow rate	10 L/min
	Pressure	0.15 MPa - 0.2 MPa
	Connectors	PFA 3/4(For Polish side) PFA 3/4(For Transfer/Cleaning Unit)

3. Slurry	Pressure	Max. 0.15-0.2 MPa
	Connection	PFA 3/8 x 6 (6 Ports) OD 9.53x ID 6.33
4. Chemical supply for each cleaner	Pressure	Max. 0.15-0.2 MPa
	Connection	PFA 3/8 x 2 (2 Ports)
5. Drive cooling water	Flow rate	10 l/min (2x 5l/min)
	Inlet pressure	Max 0.15 MPa, Min 0.1 MPa
	Outlet pressure	Max. 0.05MPa
	Temperature	18 – 22 °C
	Connection	3/8swagelok x 2(both inlet/outlet) x2 table
6. C.D.A.	Pressure	Max 0.8 MPa, Min 0.6 MPa
	Minimum Flow rate	120 liter/min (ANR)
	Connection	3/8 swagelok
7. Nitrogen Gas (BACKSIDE PRES	Pressure	Max 0.6 MPa, Min 0.4 MPa
	Minimum Flow rate	40 liter/min (ANR)
	Connection	3/8 swagelok
8. Vacuum	Pressure	Max -90kPa, Min -83kPa
	Minimum Flow rate	15 liter/min
	Connection	3/8 swagelok
9.Chemical drains		
1) 2nd cleaner(L) & wet station	Maximum Flow rate	10 liter/min
	Connection	NPT 1-1/4 Female
2) Other cleaner	Maximum Flow rate	8 liter/min per cleaner
	Connection	NPT 3/4 Female
3) Drain Pan	Drain NPT1/2	n.a.
4) Waste slurry drain (Polishing side	Maximum Flow rate	32 liter/min (16 liter/min each table)
	Connection	NPT 1 1/2 Female
10. Exhaust		
A. Each cleaner	Minimum pressure	-300 Pa
	Exhaust volume	Max 4 m3/min, Min 3.2
	Connection	75 OD / 67 ID PVC pipe x 4
B. Local exhaust of polish unit	Minimum pressure	-300 Pa
	Exhaust volume	Max 12 m3/min, Min 10
	Connection	370 OD / 350 ID PVC pipe qty 1